

S/N: TBA

4/12/2001

DOCKET NO.: L/M-102-DIV

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: St v M. Danziger, et al.

Serial No.: TO BE ASSIGNED

Art Unit: TO BE ASSIGNED

Divisional of 09/321,565

Filed: April 12, 2001

Examiner: TO BE ASSIGNED

For: Method and Apparatus for Evaluating a Known Good Die Using
Both Wire Bond and Flip-Chip Interconnects

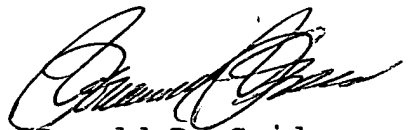
LETTER TO OFFICIAL DRAFTSPERSON

Assistant Commissioner of
Patents and Trademarks
Washington, D.C. 20231

Sir:

Attached are 2 sheets of drawings to be corrected as shown in
red.

Respectfully submitted,



Ronald R. Snider
Reg. No. 24,962

Date: April 12, 2001

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